

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	293	pattern formation substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/18 08:00
S2	182	pattern formation substrate and @pd<="20050224"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/18 08:01
S3	139	pattern formation substrate and @pd<="20030605"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/18 08:02
S7	14	nakabayashi, takaya.inv.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 10:06
S8	342017	(Wire\$ or wiring or circuit\$1 or circuitry or (thin near2 film near3 transistor) or (TFT)) near3 (pattern\$1 or arrangement\$1 or patterning)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:53
S9	120418	(Wire\$ or wiring or circuit\$1 or circuitry or (thin near2 film near3 transistor) or (TFT)) near3 (pattern\$1 or arrangement\$1 or patterning)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:53
S10	932	(Wire\$ or wiring or circuit\$1 or circuitry) near3 inkjet	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:54
S11	3039	(Wire\$ or wiring or circuit\$1 or circuitry) near5 (inkjet or (ink near3 jet))	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:55
S12	280325	(pattern\$1 or arrangement \$1 or patterning) near3 (formation\$2 or form\$3 or configuration\$1 or template \$1 or mold\$1 or design\$1 or configur\$3)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:56

S13	16877	(liquid\$1 or ink\$1 or drop\$1 or droplet\$1) near5 (eject\$3 or flow\$3 or discharge\$3 or move\$1 or moving or run\$1 or running or discharging or pour\$3 or expel or expel\$4) near4 (line\$1 or band\$1 or tracing\$1 or channel\$1 or groove\$1 or course\$1 or route\$1 or trough\$1 or conduit\$1 or duct\$1 or furrow\$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:56
S14	210	(Wire\$ or wiring or circuit\$1 or circuitry or (thin near2 film near3 transistor) or (TFT)) near3 (contact near3 angle)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:57
S15	38563	S9 and S12	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:59
S16	26	S9 and S12 and S13	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 13:59
S17	0	2000-33698	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 14:00
S18	1	"200033698"	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 14:00
S19	1	"20030059686"	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 14:01
S20	26242	((Print\$2 or printing or image\$1 or imag\$3 or surface\$1) near4 (hydrophobic or hydrophilic or (water near4 affinity) or wettability))	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 14:13
S21	274	S9 and S11	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 14:14
S22	152	S9 and S11 and S12	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 14:14
S24	1	S9 and S11 and S12 and S20	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 14:15

S29	221599	(Wire\$ or wiring or circuit\$1 or circuitry or (thin near2 film near3 transistor) or (TFT)) near3 (pattern\$1 or arrangement\$1 or patterning)	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:24
S30	6290	(Wire\$ or wiring or circuit\$1 or circuitry) near5 (inkjet or (ink near3 jet))	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:25
S31	559091	(pattern\$1 or arrangement \$1 or patterning) near3 (formation\$2 or form\$3 or configuration\$1 or template \$1 or mold\$1 or design\$1 or configur\$3)	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:26
S32	60216	(liquid\$1 or ink\$1 or drop\$1 or droplet\$1) near5 (eject\$3 or flow\$3 or discharge\$3 or move\$1 or moving or run\$1 or running or discharging or pour\$3 or expel or expel\$4) near4 (line\$1 or band\$1 or tracing\$1 or channel\$1 or groove\$1 or course\$1 or route\$1 or trough\$1 or conduit\$1 or duct\$1 or furrow\$1)	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:26
S33	1654	S29 and S30	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:27
S34	93447	S29 and S31	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:28
S35	661	S29 and S30 and S31 and S32	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:28
S36	3	S29 same S30 same S31 same S32	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:28
S37	3311	(Wire\$ or wiring or circuit\$1 or circuitry or (thin near2 film near3 transistor) or (TFT)) near3 (pattern\$1 or arrangement\$1 or patterning) and "427".clas.	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:30
S38	17	S35 and ("427".clas. or "428".clas.)	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:30
S39	1	"10525614"	US-PGPUB; USPAT	ADJ	ON	2008/04/02 14:55
S40	452	((((liquid or fluid or water or ink) near3 (pattern or patterning)) with surface) same (gravity or fall\$3 or project\$3)	US-PGPUB; USPAT	ADJ	ON	2008/04/02 16:11

S41	49	((liquid or fluid or water or ink) near3 (fountain or spray) near5 (slide or channel) near5 (pattern\$1 or patterning\$1))	US-PGPUB; USPAT	ADJ	ON	2008/04/02 16:22
S42	472	((liquid or fluid or water or ink) near3 (fountain or spray or flow) near5 (slide or channel) near5 (pattern\$1 or patterning\$1))	US-PGPUB; USPAT	ADJ	ON	2008/04/02 16:25
S43	209	S42 and (drop\$1 or droplet \$1)	US-PGPUB; USPAT	ADJ	ON	2008/04/02 16:36
S44	0	S42 and (drop\$1 or droplet \$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/02 16:57

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